

2 003 054285

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization  
International Bureau(43) International Publication Date  
26 September 2002 (26.09.2002)

PCT

\*162162\*  
(10) International Publication Number  
WO 02/075926 A3(51) International Patent Classification<sup>7</sup>: H03K 19/173,  
G11C 5/06, 29/00

(21) International Application Number: PCT/US02/07916

(22) International Filing Date: 15 March 2002 (15.03.2002)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:  
09/809,537 15 March 2001 (15.03.2001) US(71) Applicant: MICRON TECHNOLOGY, INC. [US/US];  
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LLP, One Dayton Centre - Suite 500, One South Main  
Street, Dayton, OH 45402-2023 (US).(81) Designated States (national): AE, AG, AL, AM, AT, AU,  
AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU,CZ, DE, DK, DM, DZ, EC, EE, ES, FI, GB, GD, GE, GH,  
GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC,  
LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW,  
MX, MZ, NO, NZ, OM, PH, PL, PT, RO, RU, SD, SE, SG,  
SI, SK, SL, TJ, TM, TN, TR, TT, TZ, UA, UG, UZ, VN,  
YU, ZA, ZM, ZW.(84) Designated States (regional): ARIPO patent (GH, GM,  
KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW),  
Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM),  
European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR,  
GB, GR, IE, IT, LU, MC, NL, PT, SE, TR), OAPI patent  
(BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR,  
NE, SN, TD, TG).

## Published:

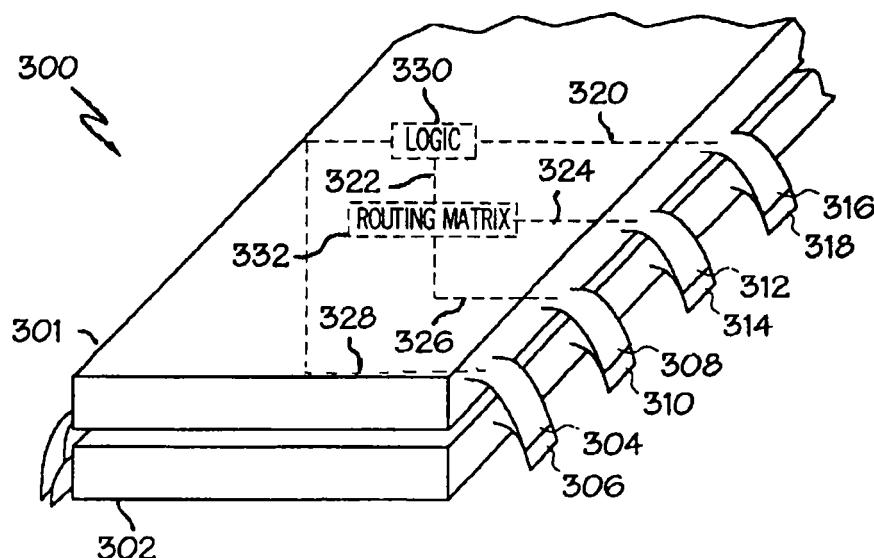
- with international search report
- with amended claims

(88) Date of publication of the international search report:  
6 November 2003

Date of publication of the amended claims: 18 December 2003

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: ANTIFUSE REROUTE OF DIES



(57) Abstract: A semiconductor die is provided with an internally programmable router to assign signal paths to select connection points. A switching matrix incorporating at least one antifuse is utilized to selectively route signal paths on the semiconductor die. The chips can then be used individually, for example to reconfigure chip pin assignments to operate in a plurality of different socket layouts, or where features or controls of a chip are selectively enabled or disabled. A further alternative involves programming a first chip, then stacking piggyback, or one on top of the other, the first chip onto a second chip. The contact pins are electrically coupled together, thus avoiding the need for external frames and pin rerouting schemes to form stacked chips. In the stacked chip configuration, control pins are rerouted to align with unused pins on the chip stacked against.

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